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MD21605B6W-FPTLW I 3 2 x 16		3.79mm Character Height	LCD Modu l e		
Specification					
Version: 1		Date: 01/08/2020			
		Revision			
1	29/07/2020	First Issue			

Disp l ay F	Display Features					
Character Count	2 x 16					
Appearance	Black on White					
Logic Voltage	3V					
Interface	I2C		1			
Font Set			MIS			
Display Mode	Transf l ective		ROHS ompliant			
Character Height	3.79 <mark>mm</mark>	C	omphant			
LC Type	FSTN					
Module Size	66.00 x 28.00 x 9.30 mm					
Operating Temperature	-20°C ~ +70°C					
Construction	manuta cob	Box Quantity	Weight / Disp l ay			
LED Backlight	White		2 6 4			

* - For full design functionality, please use this specification in conjunction with the ST7032i specification. (Provided Separately)

Display Accessories					
Part Number	Description				

Optional Variants						
Fonts	Appearances	Voltage				
		3V				

General Specification

The Features is described as follow:

■ Number of Characters: 16 characters x 2 Lines

■ Module dimension: 66.0 x 28.0 x 9.3 mm

■ View area: 40.0 x 9.98 mm

Active area: 38.0 x 7.98 mm

■ Dot size: 0.36 x 0.43 mm

■ Dot pitch: 0.41 x 0.48 mm

■ Character size2.00 x 3.79 mm

■ Character pitch2.40 x 4.19 mm

■ LCD type: FSTN Positive Transflective

■ Duty: 1/16 , 1/5 Bias

■ View direction: 6 o'clock

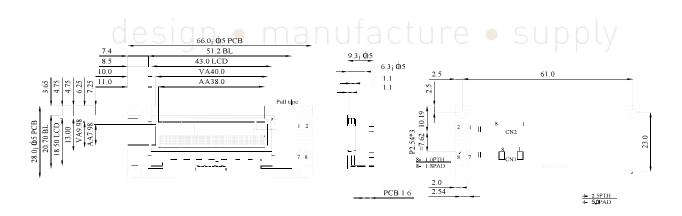
■ Backlight Type: LED White ■ manufacture ■ SUPPLY

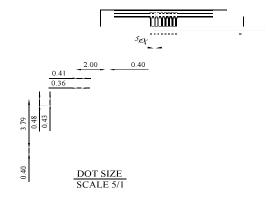
■ IC: ST7032i

Interface Pin Function

Pin No.	Symbol	Level	Description
1	VDD	Р	Power supply
2	VSS	Р	Ground
3	SDA	-	(In I2C interface DB7 (SDA) is input data. SDA and SCL must connect to I2C bus (I2C bus is to connect a resister between SDA/SCL and the power of I2C bus).
4	SCL	-	(In I2C interface DB6 (SCL) is clock input. SDA and SCL must connect to I2C bus (I2C bus is to connect a resister between SDA/SCL and the power of I2C bus).
5	RST	-	RESET (Low active)
6	Α	-	LED+
7	К	- /	LED-
8	NC	-/	No Connection

Contour Drawing





PIN NO.	SYMBOL	PIN NO.	SYMBOL
1	VDD	5	RST
2	VSS	6	Α
3	SDA	7	K
4	SCL	8	NC

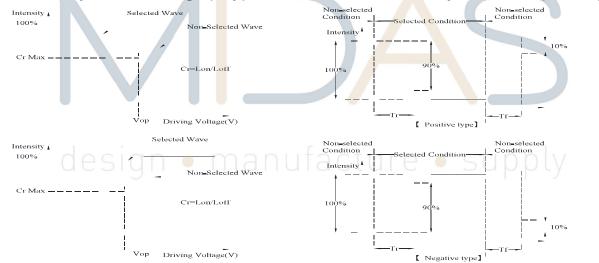
The non-specified tolerance of dimension is $\,\pm 0.3 \mathrm{mm}.$

Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0		30	ψ= 180°
View Ang l e	θ	CR≧2	0	_	60	ψ= 0°
	θ CR≧2		0	_	45	ψ= 90°
	θ	CR≧2	0	_	45	ψ= 270°
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	150	200	ms
	T fa ll	_	_	150	200	ms



Definition of Response Time (Tr, Tf)

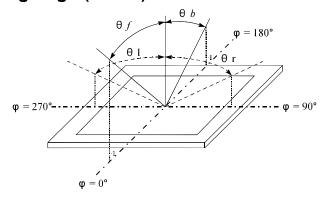


Conditions:

Operating Voltage : Vop Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≧2)



Absolute Maximum Ratings

Item	Symbol	Min	Тур	Мах	Unit
Operating Temperature	Тор	-20	ı	+70	°C
Storage Temperature	Тѕт	-30	_	+80	°C
Input Voltage	VIN	-0.3	_	V _{DD} +0.3	V
Power Supply Voltage	V _{DD} -V _{SS}	-0.3		+6.0	V
LCD Driver Voltage	V _{LCD}	2.7	_	7.0	V

Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	_	3	3.3	3.5	V
		Ta=-20℃		_		٧
Supply Voltage For LCD	VLCD	Ta=25 ℃	4.3	e ^{4.5} S	4.7	V
40019		Ta=70°C			<u> </u>	V
Input High Volt.	VIH	_	0.7 V _{DD}	1	V _{DD}	٧
Input Low Volt.	VIL	_	_		0.2 V _{DD}	٧
Output High Volt.	Vон	—	0.8 V _{DD}		V _{DD}	٧
Output Low Volt.	Vol	_	_	_	0.2V _{DD}	٧
Supply Current(No						
include	I DD	_	_	0.2	1	mA
LED Backlight)						

Note1: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

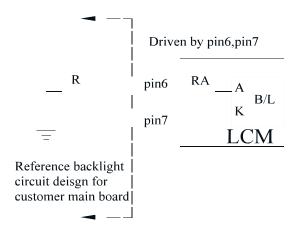
Backlight Information

Specification

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition
Supply Current	ILED	10	32	40	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	٧	ILED=32mA
Reverse Voltage	VR	_	_	5	٧	_
Colour	Х	0.27	0.29	0.31	_	ILED=32mA
Coordinate	Υ	0.28	0.30	0.32	_	ILED-32MA
Luminance	IV	1080	1350		od/m²	ILED=32mA
(Without LCD)	IV	1000	1350		Cu/III-	ILED-32IIIA
LED Life Time						ILED=32mA
(For Reference	_/	-	50K	-)	Hr.	<mark>25℃,50-60%RH,</mark>
only)	V					(Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



Reliability

Content of Reliability Test (Wide temperature, -20°c~70°C)

Environmental Test							
Test Item	Content of Test	Test Condition	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1				
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2				
Therma l shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	I tem			Criterion		AQL	
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 					
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 					
	LCD black spots, white	3.1 Round type: $\Phi = (x + y) / 2$ X		$\phi \le 0.10$ $0.10 < \phi \le 0.20$ $0.20 < \phi \le 0.25$ $0.25 < \phi$	Acceptable Q TY Accept no dense 2 1 0	2.5	
03	spots, contamination (non-display)	3.2 Line type : (A	Length L≦3.0 L≦2.5	width W≤0.02 0.02 <w≤0.03 0.03<w≤0.05="" 0.05<w<="" td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w≤0.03>	Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are vis judge using black specifications, no to find, must che specify direction.	k spot ot easy ck in	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5	

NO	I tem	Criterion					
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
05	Chipped glass	Symbols Define: x: Chip length y: 0 k: Seal width t: 0 L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sur z: Chip thickness Z≤1/2t 1/2t < z ≤ 2t	Chip width z: Chip Glass thickness a: LCI :	thickness D side length n panels: x: Chip length x≤1/8a	2.5		
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a			
		⊙If there are 2 or more	chips, x is the total leng	gth of each chip.			

NO Ite	em	Criterion A						
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:						
I 06 I	ass ack	y≤0.5mm 6.2.2 Non-conductive portion:	pected according at sea l ed by the	g to electrode terminal customer, the alignment	2.5			

NO	Item	Criterion			
07	Cracked glass	The LCD with extensive crack is not acceptable.			
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 			
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65		
10	PCB, COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 0.65 0.65 2.5 2.5		
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65		

NO	Item	Criterion				
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5			
		12.2 No cracks on interface pin (OLB) of TCP.	0.65			
		12.3 No contamination, solder residue or solder balls on product.	2.5			
		12.4 The IC on the TCP may not be damaged, circuits.	2.5			
		12.5 The uppermost edge of the protective strip on the interface	2.5			
	Genera l appearance	pin must be present or look as if it cause the interface pin to				
12		sever. 12.6 The residual rosin or tin oil of soldering (component or chip	2.5			
		component) is not burned into brown or black color.	2.5			
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65			
		12.8 Pin type must match type in specification sheet.	0.65			
		12.9 LCD pin loose or missing pins.	0.65			
		12.10 Product packaging must the same as specified on packaging specification sheet.				
		12.11 Produ <mark>ct</mark> dimension and structu <mark>re</mark> must conform to product	0.65			
		specification sheet.				
		12.12 Visua <mark>l d</mark> efect outside of VA is not considered to be rejection.				

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Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

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Material List of Components for RoHs

1. Midas Displays hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Materia l	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Va l ue	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.: 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.